STAUF XP 40

Low-dust, cement-based filling and levelling compound

Technical Datasheet

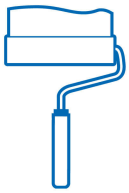
Product number	✓ 133020
Special features	✓ low-dust ✓ coverings can be laid after a very short time ✓ suitable for wood flooring ✓ till 40 mm layer thickness
Application range	✓ levelling of floor screeds before bonding with STAUF wood flooring adhesives and adhesives for textile and elastic floorings
Suitable sub floors	✓ sanded mastic asphalt screed ✓ concrete C 25 / 30 according to DIN 1045 (non-skid surface) ✓ calcium sulphate (flow) floors ✓ wooden planks, wood fibre boards ✓ magnesite and plaster floors ✓ chipboards V100 (E1), OSB boards ✓ stone, ceramic, terrazzo, tiles ✓ cement floors
Suitable primers	✓ STAUF VDP 130 ✓ STAUF VPU 155 S STAUF quartz sand ✓ STAUF D 54 ✓ STAUF VDP 160 ✓ STAUF VEP 195 STAUF quartz sand
Product properties	✓ up to 1 mm suitable for chair rollers according to DIN EN 12529 ✓ suitable on sub floor heating systems ✓ good absorbency ✓ ductile during processing ✓ high strength ✓ pumpable ✓ self-levelling ✓ tension reducing ✓ with STAUF reinforcing fibres also suitable for use on surfaces that are not dimensionally stable
Color	✓ light grey

Consumption in g/m² per mm layer thickness	✓ 1500g per mm layer thickness
Accessibility/ready for foot traffic	✓ after 2 hours at 20 °C, max 65% rel. humidity
Ready for installation	✓ after 12 hours at 20 °C, (with 2 mm layer thickness) max 65% rel. humidity ✓ after 24 hours at 20 °C, (with 10 mm layer thickness) max 65% rel. humidity ✓ after 48 hours at 20 °C, (with 20 mm layer thickness) max 65% rel. humidity ✓ after 72 hours at 20 °C, (with 40 mm layer thickness) max 65% rel. humidity
Additional instructions 1	✓ On chipboards / OSB boards: Add STAUF reinforcing fibres to levelling compound ✓ Behaviour in fire, DIN 4102: A2 and DIN EN 13501: A2fl-S1
Room climate at work site	✓ minimum 15 °C, maximum 75% rel. humidity, preferably max. 65%
Transport hazard category	✓ -
Storage requirements	✓ dry
Shelf-life	✓ 9 months
Giscode	✓ ZP1
Emicode	✓ EC1-R plus
Available packaging	✓ 25 kg paper bag
layer thickness	✓ minimum 1 mm below floor coverings ✓ min. 2 mm below wood flooring ✓ 0,5 - 40 mm without aggregate ✓ 3 - 40 mm with reinforcing fibres ✓ 20 – 40 mm with aggregates ✓ mastic asphalt screed 2-5 mm
Processing time	✓ approx. 30 minutes at 20 °C and 65% rel. humidity
Mixing ratio component A	✓ 25 kg levelling compound ✓ Layer thickness 20 - 40 mm: 25 kg levelling compound and 6 - 18 kg quartz sand ✓ Fibre reinforcement: 25 kg filling compound and 250 g STAUF reinforcing fibres
Mixing ratio component B	✓ layer thickness up 20 mm: 6,5 liter water ✓ layer thickness at 20 mm: 6 liter water

EXAMINATION OF SUB FLOOR

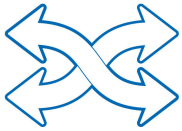
Prior to processing, the sub floor must be checked according to the standard DIN 18356, DIN 18365, DIN 18367 or corresponding national standards. The sub floor shall be resistant to pressure and tension, free of cracks, must have sufficient surface strength, be permanently dry, level, clean and free of anti-adherents, sinter layers etc. In addition, porosity and grip of surface need to be checked. Also check moisture content and absorptive capacity of cement (flow) and calciumsulfate (flow) floors as well as room temperature, air humidity and sub floor temperature.

SUB FLOOR PREPARATION



It must be ensured that the sub floor is ready for installation by performing proper sub floor preparation, floors must be clean, have sufficient surface strength, must be level, permanently dry and free of cracks. A mechanical pretreatment of the subfloor (sweeping, vacuuming, mechanical brushing, sanding, milling, shot blasting) must be performed depending on type and condition of sub floor. Cracks and joints, except expansion joints and other construction joints, shall be solidly closed with STAUF casting resin and floor brackets. Cavities and indentations can be filled with a non self-levelling STAUF levelling compound. In order to improve adhesion of adhesives and leveling compounds, prime the sub floor with the appropriate primer.

MIXING PROCEDURE OF COMPONENTS

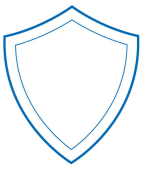


Add specified amount of water (clean and cold) into clean mixing bucket. Add complete content of container and stir evenly. For mixing, use an electrical stirrer with approx. 600 - 800 rpm with spiral or large paddle mixer. Mix until you have a homogeneous compound. Mix for another two minutes, wait one minute and then stir again for one minute (does NOT apply for non-self levelling compounds). Extending the levelling compound: To achieve higher layer thickness, the levelling compound can be extended with STAUF quartz sand. For reinforced levelling compound: Add 1 pouch (250 g) STAUF reinforcement fibers after initial stirring and then stir again for 2 minutes.

PROCESSING

Apply self-levelling compound within specified processing time. Do not pour the compound from mixing beaker on one spot only, but spread over a surface of approx. 2 x 2 m by changing position during pouring. Layer thickness can be controlled by using a wiper or a smoothing trowel. Air the levelling compound using a prickle roller. Self-levelling compounds do not require any additional mechanical spreading and form an even surface by themselves. Lower temperatures or higher ambient humidity delay the period until floor is ready for installation. The compound sets hydraulically, which means that it needs to be protected from direct sunlight and draughts. Before applying a further layer of filler or levelling compound, apply an intermediate layer of STAUF dispersion primer for filler compounds. Do not prime levelling and filler compounds before direct adhesion. For chipboard and OS panels, layer thicknesses of up to 5 mm are admissible. On less absorbent substrates and under flexible coverings, layer thickness of at least 2 mm.

LIMITATION OF LIABILITY



The foregoing representations are based on the results of our most current product and material testing and are of a non-obligatory advisory nature only since we have no control over the actual quality of workmanship, materials used and worksite conditions. As such, they do not constitute an express or implied warranty of any kind. The same applies to our commercial and technical consultation services which are provided free-of-charge and without obligation. Therefore, we strongly recommend that prior on-site testing be conducted to observe and study the suitability of the product for the intended purpose. With the release of this technical information, all prior technical information (technical data sheets, installation recommendations and other information regarding similar purposes) becomes invalid.

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